# **TOSHIBA**

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## RD Number: RD149

RD Title: TB67B008FNG Evaluation circuit BOM

Item No.	Designator	Quantity	Value	Part Number	Manufacturer	Description	Package	Not Mount
1	R1	1	0.2Ω 1W	-	-	Leaded resistor		
2		0	0.2Ω 1W	-	-	Chip resistor		√
3	R2	1	100kΩ 0.25W	-	-	Leaded resistor		
4		0	100kΩ 0.25W	-	-	Chip resistor		√
5	R3	1	20kΩ 0.25W	-	-	Leaded resistor		
6		0	20kΩ 0.25W	-	-	Chip resistor		$\checkmark$
7	R4	1	1kΩ 0.25W	-	-	Leaded resistor		
8		0	1kΩ 0.25W	-	-	Chip resistor		√
9	R5	1	100kΩ 0.25W	-	-	Leaded resistor		
10		0	100kΩ 0.25W	-	-	Chip resistor		$\checkmark$
11	R6	1	100kΩ 0.25W	-	-	Leaded resistor		
12		0	100kΩ 0.25W	-	-	Chip resistor		√
13	R7	1	100kΩ 0.25W	-	-	Leaded resistor		
14		0	100kΩ 0.25W	-	-	Chip resistor		$\checkmark$
15	R8	1	0Ω	-	-	Leaded resistor		
16		0	0Ω	-	-	Chip resistor		√
17	R9	1	Ω0	-	-	Leaded resistor		
18		0	Ω0	-	-	Chip resistor		√
19	R10	0	Not mount	-	-	Leaded resistor		$\checkmark$
20		0	Not mount	-	-	Chip resistor		√
21	R11	1	Ω0	-	-	Leaded resistor		
22		0	Ω0	-	-	Chip resistor		√
23	R12	0	Not mount	-	_	Leaded resistor		$\checkmark$
24		0	Not mount	-	-	Chip resistor		√
25	R13	0	Not mount	-	-	Leaded resistor		√
26		0	Not mount	-	-	Chip resistor		√

27	R14	0	Not mount	-	-	Leaded resistor	$\checkmark$
28		0	Not mount	-	-	Chip resistor	$\checkmark$
29	R15	0	Not mount	-	-	Leaded resistor	$\checkmark$
30		0	Not mount	-	-	Chip resistor	$\checkmark$
31	R16	0	Not mount	-	-	Leaded resistor	$\checkmark$
32		0	Not mount	-	-	Chip resistor	$\checkmark$
33	R17	0	Not mount	-	-	Leaded resistor	$\checkmark$
34		0	Not mount	-	-	Chip resistor	$\checkmark$
35	C1	1	10µF 50V	-	-	Electrolytic capacitor	
36		0	10µF 50V	-	-	Chip capacitor	$\checkmark$
37	C2	1	0.1µF 50V	-	-	Capacitor	
38		0	0.1µF 50V	-	-	Chip capacitor	$\checkmark$
39	C3	1	0.1µF 50V	-	-	Capacitor	
40		0	0.1µF 50V	-	-	Chip capacitor	$\checkmark$
41	C4	1	180pF 50V	-	—	Capacitor	
42		0	180pF 50V	-	_	Chip capacitor	$\checkmark$
43	C5	1	1nF 50V	-	_	Capacitor	
44		0	1nF 50V	-	_	Chip capacitor	$\checkmark$
45	C6	1	0.1µF 50V	-	_	Capacitor	
46		0	0.1µF 50V	-	_	Chip capacitor	$\checkmark$
47	C7	1	0.1µF 50V	-	_	Capacitor	
48		0	0.1µF 50V	_	_	Chip capacitor	$\checkmark$
49	SW1	1	Pin header 3P	_	_	Jumper	
50		1	Jumper socket	-	_	Short pin	
51	SW2	1	Pin header 3P	-	_	Jumper	
52		1	Jumper socket	-	_	Short pin	
53	VR1	0	100kΩ 0.5W	-	_	Variable Resistor	$\checkmark$
54	VR2	0	100kΩ 0.5W	-	_	Variable Resistor	$\checkmark$
55	VR3	0	100kΩ 0.5W	-	_	Variable Resistor	$\checkmark$
56	VR4	0	100kΩ 0.5W	-	-	Variable Resistor	✓
57	VR5	1	100kΩ 0.5W	-	-	Variable Resistor	
58	VR6	1	100kΩ 0.5W	-	-	Variable Resistor	
59	VR7	1	100kΩ 0.5W	-	-	Variable Resistor	
60	J1	1	GND	-	-	Short	

61	СОМ	1	Check terminal	_	_	Check terminal	Ι	
62	U	1	Check terminal	_	_	Check terminal		
63	V	1	Check terminal	_	_	Check terminal		
64	W	1	Check terminal	_	_	Check terminal		
65	GND	4	Check terminal	_	_	Check terminal		
66	VM	1	Check terminal	-	-	Check terminal		
67	FG_OUT/LD_OUT	1	Check terminal	-	_	Check terminal		
68	TSP	1	Check terminal	-	-	Check terminal		
69	VREG	1	Check terminal	-	-	Check terminal		
70	SEL_ADJ	1	Check terminal	-	-	Check terminal		
71	ADJ0	1	Check terminal	-	-	Check terminal		
72	ADJ1	1	Check terminal	-	-	Check terminal		
73	ADJ2	1	Check terminal	-	-	Check terminal		
74	VST	1	Check terminal	-	-	Check terminal		
75	TIP	1	Check terminal	-	—	Check terminal		
76	LA	1	Check terminal	-	-	Check terminal		
77	FPWM	1	Check terminal	-	-	Check terminal		
78	OSCCR	1	Check terminal	-	-	Check terminal		
79	TRE	1	Check terminal	-	-	Check terminal		
80	TSTEP	1	Check terminal	-	_	Check terminal		
81	TEST	0	Check terminal	-	_	Check terminal		$\checkmark$
82	RS	1	Check terminal	-	_	Check terminal		
83	FST	1	Check terminal	-	_	Check terminal		
84	COM+R4	1	Check terminal	_	-	Check terminal		
85	CN2	0	Not mount	_	_			$\checkmark$
86	IC	1	TB67B008FTG	TB67B008FTG	TOSHIBA	Motor driver IC	QFN24	

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